

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客 户: _____

PRODUCT 产 品: _____ SAW FILTER

MODEL NO 型 号: _____ HDBF14008C64 SF6-4

PREPARED 编 制: _____ CHECKED 审 核: _____

APPROVED 批 准: _____ D A T E 日 期: _____ 2009-5-19

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. SCOPE

This specification shall cover the characteristics of SAW filter BF14008C64

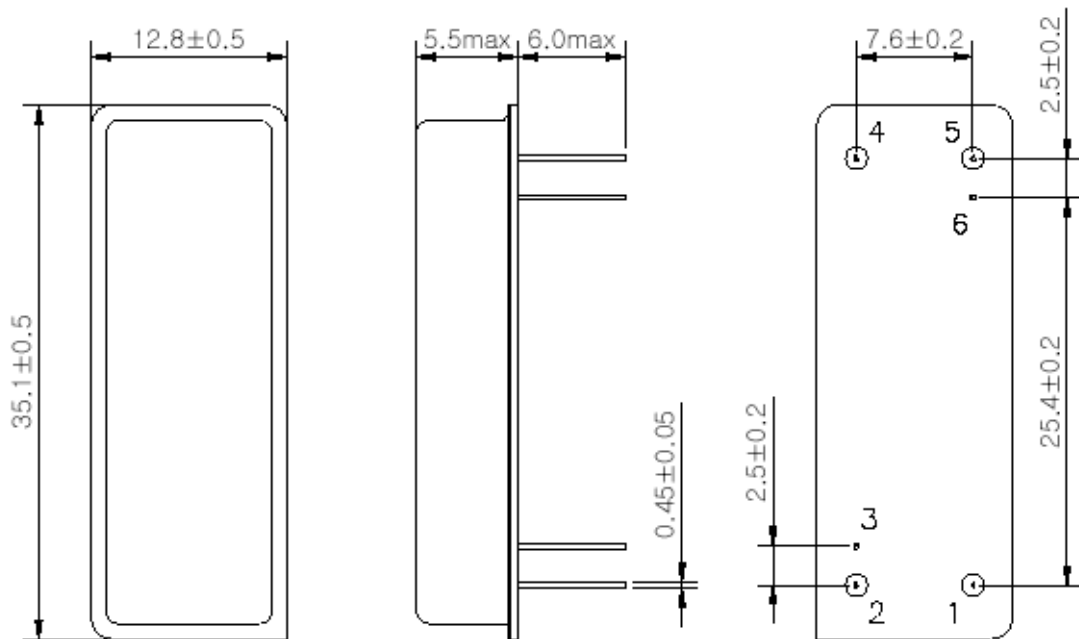
2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40℃ to +85℃
Storage temperature	-45℃ to +85℃
RF Power Dissipation	10dBm

2.2Electronic Characteristics

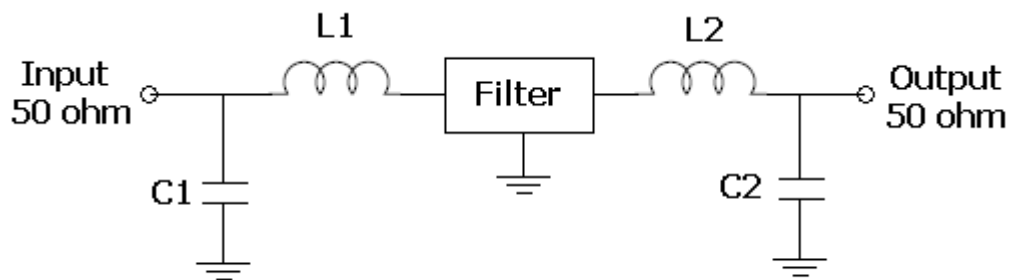
Parameter	Min	Typ	Max	Units
Center Frequency	139.92	140	140.08	MHz
Insertion Loss	-	27	30	dB
-1.5dB Bandwidth	7.7	7.78	-	MHz
-3dB Bandwidth	7.9	8	-	MHz
-10dB Bandwidth	-	8.38	8.4	MHz
-50dB Bandwidth	-	8.9	9	MHz
Passband Variation	-	1.4	2.0	dB
Absolute Delay		3.9	4	usec
Ultimate Rejection	50	55	-	dB
Material Temperature coefficient	-2.6			KHz/℃
Ambient Temperature	25			℃

3. DIMENSION



Pin Configuration	
1	Input
5	Output
2, 4	Ground
Other	Case ground

4. TEST CIRCUIT



L1=L2=22nH
C1=C2=68pF

5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85℃ for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-2 Low temperature exposure

Subject the device to -40℃ for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-3 Temperature cycling

Subject the device to a low temperature of -40℃ for 30 minutes. Following by a high temperature of +85℃ for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260℃ $\pm 10^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

5-5 Solderability

Subject the device terminals into the solder bath at 245℃ $\pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

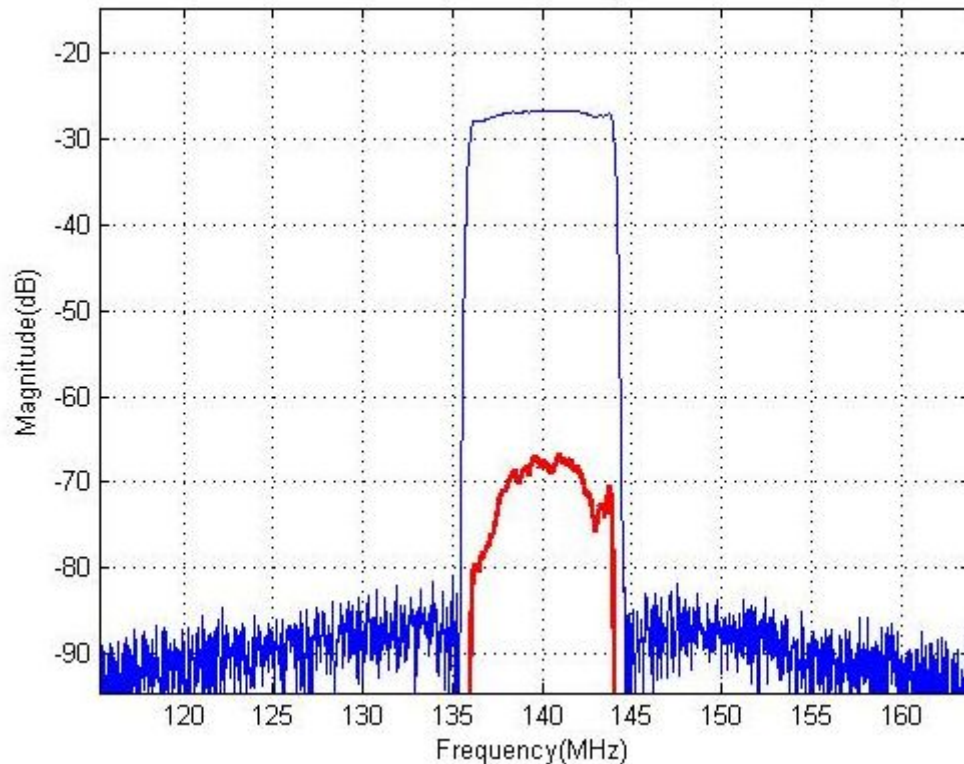
5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

6. Typical frequency response



7. REMARK

7.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

7.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

7.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.